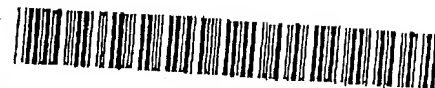


(19)



Europäisches Patentamt
European Patent Office
Office européen des brevets



(11) Publication number:

0 503 201 A2

(12)

EUROPEAN PATENT APPLICATION

(31) Application number: 91311873.9

(32) Date of filing: 20.12.91

(51) Int. Cl. 4: H01L 23/495, H01L 25/065

(33) Priority: 20.12.90 JP 404429/90
10.12.91 JP 326148/91

(43) Date of publication of application:
16.09.92 Bulletin 92/38

(54) Designated Contracting States:
DE FR GB

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(54) Semiconductor device having an interconnecting circuit board and method for manufacturing same.

(57) A semiconductor device having an interconnecting circuit board comprises an island (20) formed in a predetermined plane, a semiconductor chip (21) disposed on the island (20) and having a plurality of electrically connecting electrode pads (22), an interconnecting circuit board (23) disposed on the semiconductor chip (20) and having an electrically conductive pattern (27), a plurality of inner leads (25) disposed around the island (20), a first electrically connecting wire (26c) connecting the electrically conductive pattern (27) and one (22b) of the plurality of electrically connecting electrode pads (22), and a second electrically connecting wire (26a, 26b) connecting the electrically conductive pattern (27) and one (25a) of the inner leads (25).

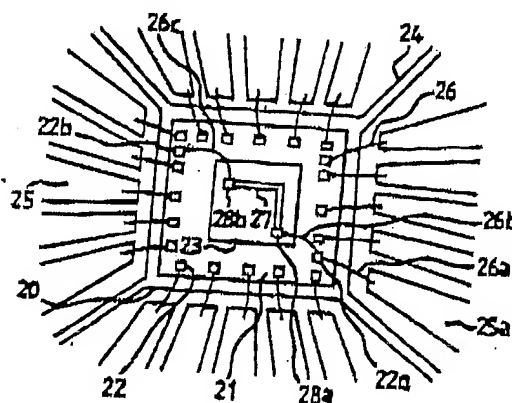


FIG. 2a

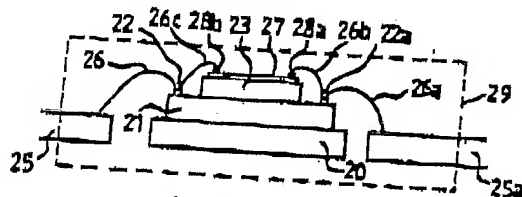


FIG. 2b